

**LIQUID CRYSTAL SEALING MATERIAL COMPOSITION**

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**Applicant:** MITSUI CHEMICALS INC

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**Abstract of JP2000347203**

**PROBLEM TO BE SOLVED:** To provide a liquid crystal sealing material composition which is capable of dealing with liquid crystal display elements (cells) produced by a single wafer press thermal adhesion system and permits the production of the homogeneous and high-quality liquid crystal display elements exhibiting high adhesive seal reliability. **SOLUTION:** The ion conductivity of an aqueous solution obtained by intimately mixing an epoxy resin composition and pure water of this liquid crystal sealing material composition is  $\leq 1$  mS/m, the viscosity of a B stage composition is 50 to 10000 Pa.s at 80 to 100 deg.C, the coefficient of thermal expansion of the cured matter of the composition is  $\leq 10 \times 10^{-5}$  mm/mm/deg.C, the thermal deformation temperature Tg is  $\geq 100$  deg.C, the 80 deg.C moisture vapor transmission rate of the cured body is  $\leq 200$  g/m<sup>2</sup>.24 hrs. The composition consists of an epoxy resin having an average  $\geq 1.2$  epoxy group in the molecule, rubber-like polymer particles (diameter below 5  $\mu$ m) of  $\leq 0$  deg.C in softening point, an inorganic filler, a thermally active latent epoxy hardener and high softening point ( $\geq 50$  deg.C) polymer particulates (diameter below 2  $\mu$ m).

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